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IDENTIFIER:

TITLE: PRINTED CIRCUIT BOARD AND ELECTRONIC COMPONENT
PACKAGE USING THE SAME

PUBN-DATE: March 15, 2002

INVENTOR-INFORMATION:

NAME	COUNTRY
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TANAKA, HIROBUMI	N/A
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KUWABARA, NAOKI	N/A
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FUJITA, KAZUTO	N/A
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MORITA, MORIJI	N/A
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ASSIGNEE-INFORMATION:

NAME	COUNTRY
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MITSUI CHEMICALS INC	N/A
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APPL-NO: JP2000257511

APPL-DATE: August 28, 2000

INT-CL (IPC): H05K001/09 , H01L023/12 , H01L023/14 , H05K003/24

ABSTRACT:

PROBLEM TO BE SOLVED: To use a Pb-free high melting point solder having a low environmental load without lowering a mounting yield by raising the degree of adhesion of a sealing resin with a plated surface.

SOLUTION: The Pb-free high melting point solder can be used by lowering a grain boundary density of an Ni-plating of a substrate by raising a mean phosphorus concentration of electroless Ni-plating to 7 to 10 wt.%, raising the degree of adhesion of an Au-plating layer of an upper layer with the sealing resin, and completing filling of a molding resin so that a molding part may not burst at a solder ball forming time.

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